



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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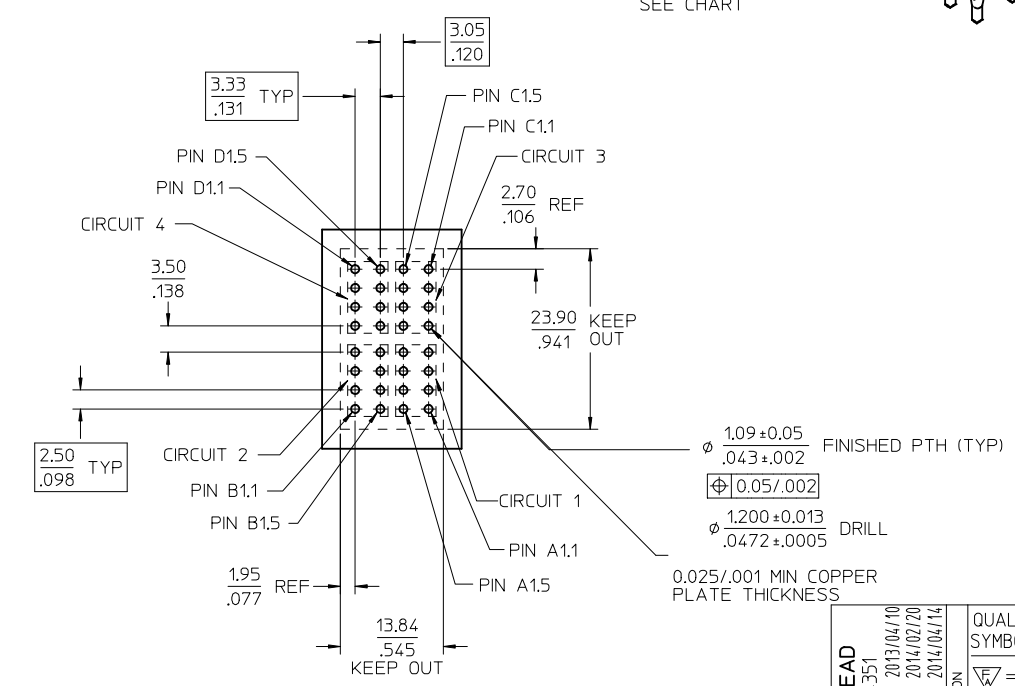
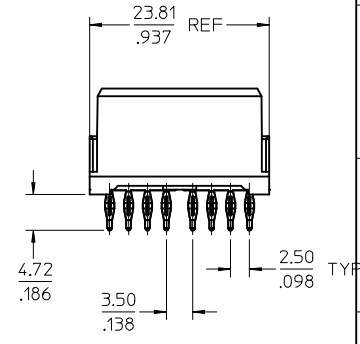
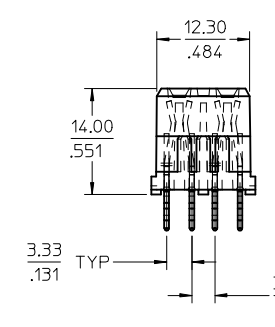
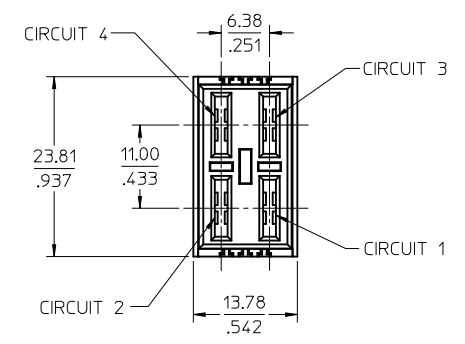
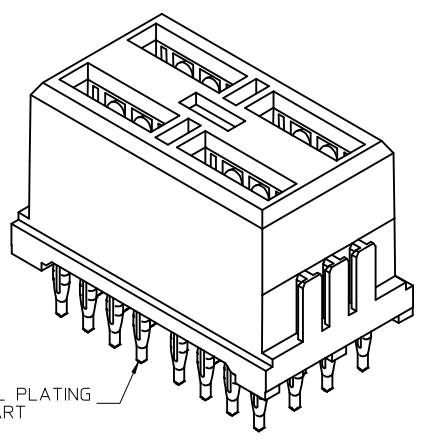
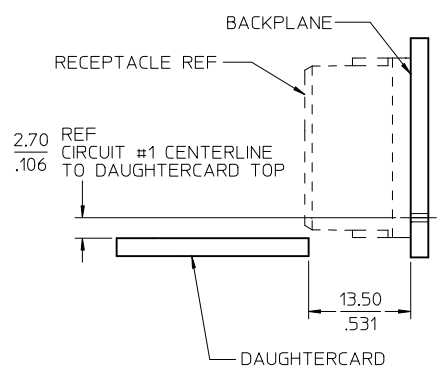
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



13	12	11	10	9	8	7	6	5	4	3	2	1
PART NUMBER	TAIL PLATING	TAIL VERSION	PLATING									
46079-1000	TIN	PRESS FIT	0.75µm/30µm MIN SELECT HARD GOLD IN CONTACT AREA WITH 2.50µm/100µm MIN SELECT TIN IN TAIL AREA OVER 1.25µm/50µm MIN NICKEL OVERALL									

NOTES:

- MATERIALS:
 - HOUSING: 30% GLASS FILLED, LCP 94V-0, COLOR BLACK
 - TERMINALS: COPPER ALLOY
 PLATING:
 - SEE CHART
 LUBRICATION: EB1 IN CONTACT AREA
- PLUG MATES WITH PLUG ASSEMBLY 46081-****
- MODULE IS DESIGNED FOR PRESS FIT TO THE PCB
- MODULE ASSEMBLY IS RoHS COMPLIANT
- MODULES TO BE UL & CSA LISTED PER UL-1977
- AVERAGE INSERTION FORCE INTO PCB IS 8.2 kg/18 lbs PER TAIL
- PRODUCT PERFORMANCE AND RATING PER PS-75431-****
- APPLICATION SPEC PER AS-75541-****
- RECOMMENDED PCB DRILL HOLE DIA 1.180/0.0465 (#56 DRILL)
- FOR MODULE CONFIGURATION SEE DRAWING SD-75541-001



PCB LAYOUT
2.40/.094 MIN THICK

REMOVE TIN/LEAD EC NO: UCP2013-4351 DRW:RWHIPPLE 2013/04/10 CHKD: BANDURA 2014/02/20 APPR: MILLER 2014/04/14	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM/IN		SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		mm	INCH	DRAWN BY	DATE	TITLE	ASSEMBLY - RECEPTACLE 4 CIRCUIT MULTI PATH molex			
REV C	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	4 PLACES	± ---	± ---	JQUILES	2005/08/01	DOCUMENT NO. SD-46079-100			
		3 PLACES	± ---	± .008	CHECKED BY	DATE				
		2 PLACES	± 0.20	± .013	MDATA	2005/08/04	SHEET NO. 1 OF 1			
		1 PLACE	± 0.33	± ---	APPROVED BY	DATE				
		0 PLACE	±	±	APATEL	2005/08/05	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
		ANGULAR ±1/2°		MATERIAL NO.		SIZE				
				SEE CHART						